



LCE P-Channel Enhancement Mode Power MOSFET

Description

The LCE1205 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

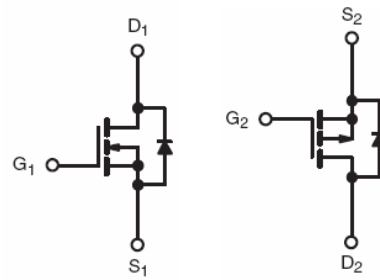
● **N-Channel**

- $V_{DS} = 12V, I_D = 5A$
- $R_{DS(ON)} < 32m\Omega @ V_{GS} = 4.5V$
- $R_{DS(ON)} < 42m\Omega @ V_{GS} = 2.5V$
- $R_{DS(ON)} < 80m\Omega @ V_{GS} = 1.8V$

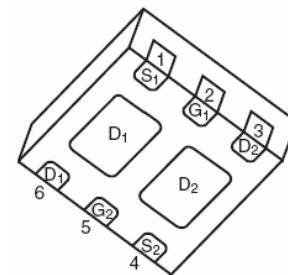
● **P-Channel**

- $V_{DS} = -12V, I_D = -5A$
- $R_{DS(ON)} < 74m\Omega @ V_{GS} = -4.5V$
- $R_{DS(ON)} < 110m\Omega @ V_{GS} = -2.5V$
- $R_{DS(ON)} < 220m\Omega @ V_{GS} = -1.8V$

● **Load Switch for Portable Devices**



N-channel P-channel



Pin assignment

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|---------|----------------|-----------|------------|----------|
| 1205 | LCE1205 | DFN2X2-6 | - | - | - |

Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

| Parameter | Symbol | N-Channel | P-Channel | Unit |
|--|----------------|-------------------|------------|-------------|
| Drain-Source Voltage | V_{DS} | 12 | -12 | V |
| Gate-Source Voltage | V_{GS} | ± 12 | ± 12 | V |
| Continuous Drain Current | I_D | $T_A=25^{\circ}C$ | 5 | -5 |
| | | $T_A=70^{\circ}C$ | 4.5 | -3.8 |
| Pulsed Drain Current ^(Note 1) | I_{DM} | 20 | -15 | A |
| Maximum Power Dissipation | P_D | 1.9 | 1.9 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | -55 To 150 | $^{\circ}C$ |

Thermal Characteristic

| | | | | |
|--|-----------------|------|----|---------------|
| Thermal Resistance, Junction-to-Ambient ^(Note2) | $R_{\theta JA}$ | N-Ch | 65 | $^{\circ}C/W$ |
| Thermal Resistance, Junction-to-Ambient ^(Note2) | $R_{\theta JA}$ | P-Ch | 65 | $^{\circ}C/W$ |

**N-CH Electrical Characteristics (T_A=25°C unless otherwise noted)**

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|---------------------|---|-----|-----|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V, I _D =250μA | 12 | 20 | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =12V, V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±12V, V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 0.4 | 0.6 | 1 | V |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} =4.5V, I _D =5A | - | 28 | 32 | mΩ |
| | | V _{GS} =2.5V, I _D =4.6A | - | 36 | 42 | mΩ |
| | | V _{GS} =1.8V, I _D =4.1A | - | 55 | 80 | mΩ |
| Forward Transconductance | g _{FS} | V _{DS} =10V, I _D =5A | - | 20 | - | S |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =6V, V _{GS} =0V, F=1.0MHz | - | 495 | - | PF |
| Output Capacitance | C _{oss} | | - | 155 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | | - | 95 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =6V, R _L =1.2Ω V _{GS} =10V, R _{GEN} =4.5Ω | - | 7.0 | - | nS |
| Turn-on Rise Time | t _r | | - | 5.0 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | - | 18 | - | nS |
| Turn-Off Fall Time | t _f | | - | 6 | - | nS |
| Total Gate Charge | Q _g | V _{DS} =6V, I _D =5A, V _{GS} =4.5V | - | 6.6 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 1 | - | nC |
| Gate-Drain Charge | Q _{gd} | | - | 1.2 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V, I _S =5A | - | - | 1.2 | V |

**P-CH Electrical Characteristics (T_A=25°C unless otherwise noted)**

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|---------------------|---|------|------|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V, I _D =-250μA | -30 | -33 | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =-12V, V _{GS} =0V | - | - | -1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±12V, V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =-250μA | -0.4 | -0.7 | -1 | V |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} =-4.5V, I _D =-4.5A | - | 60 | 74 | mΩ |
| | | V _{GS} =-2.5V, I _D =-3.2A | - | 84 | 110 | mΩ |
| | | V _{GS} =-1.8V, I _D =-1A | - | 130 | 220 | mΩ |
| Forward Transconductance | g _{FS} | V _{DS} =-10V, I _D =-5A | - | 10 | - | S |
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C _{ISS} | V _{DS} =-6V, V _{GS} =0V, F=1.0MHz | - | 520 | - | PF |
| Output Capacitance | C _{OSS} | | - | 100 | - | PF |
| Reverse Transfer Capacitance | C _{RSS} | | - | 65 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =-6V, R _L =2.3Ω V _{GS} =-10V, R _{GEN} =6Ω | - | 7.5 | - | nS |
| Turn-on Rise Time | t _r | | - | 5.5 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | - | 19 | - | nS |
| Turn-Off Fall Time | t _f | | - | 7 | - | nS |
| Total Gate Charge | Q _g | V _{DS} =-6V, I _D =-4.5A V _{GS} =-4.5V | - | 9.2 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 1.6 | - | nC |
| Gate-Drain Charge | Q _{gd} | | - | 2.2 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V, I _S =-5A | - | - | -1.2 | V |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

N- Channel Typical Electrical and Thermal Characteristics (Curves)

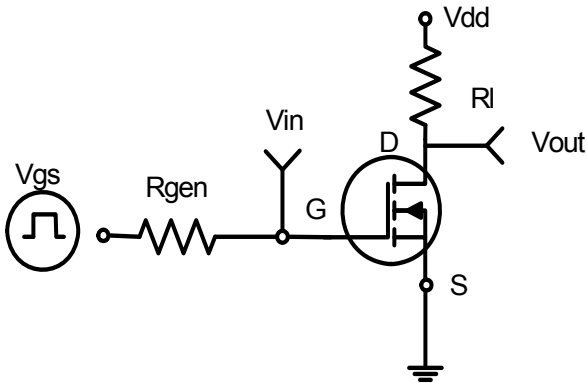


Figure 1: Switching Test Circuit

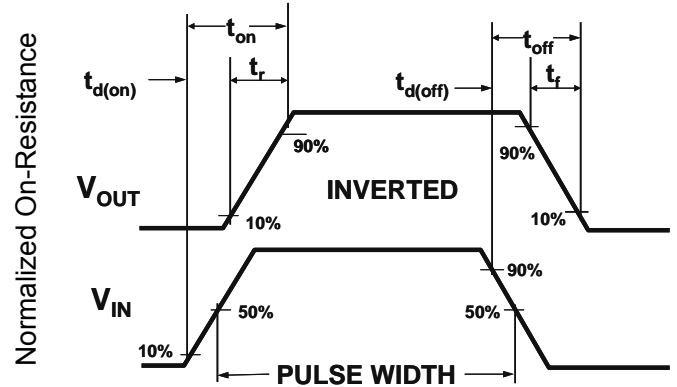


Figure 2: Switching Waveforms

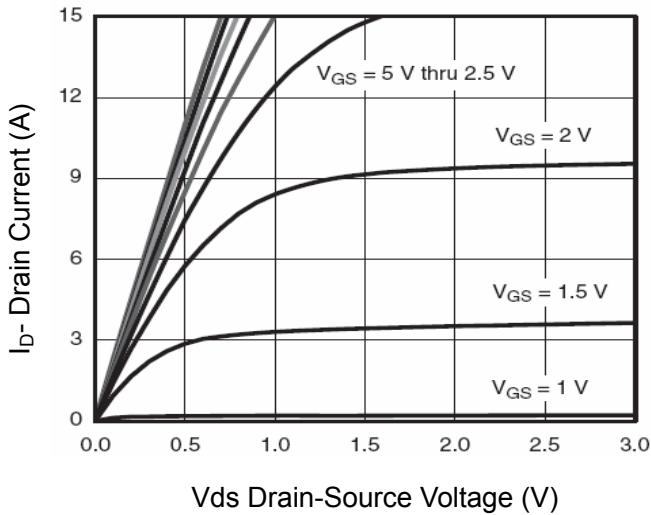


Figure 3 Output Characteristics

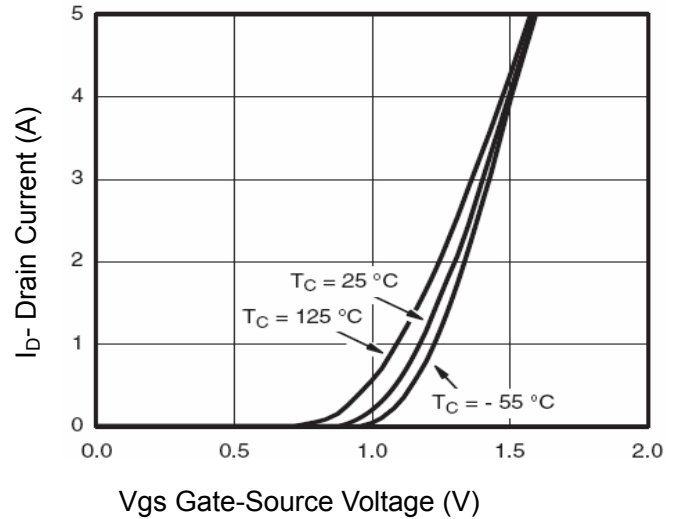


Figure 4 Transfer Characteristics

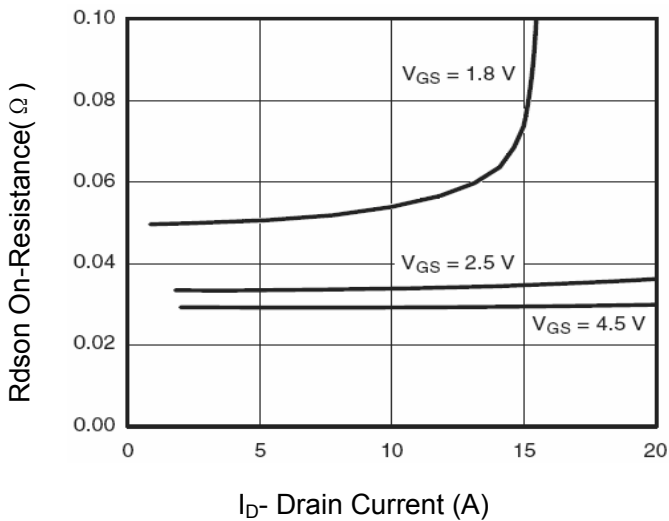


Figure 5 Drain-Source On-Resistance

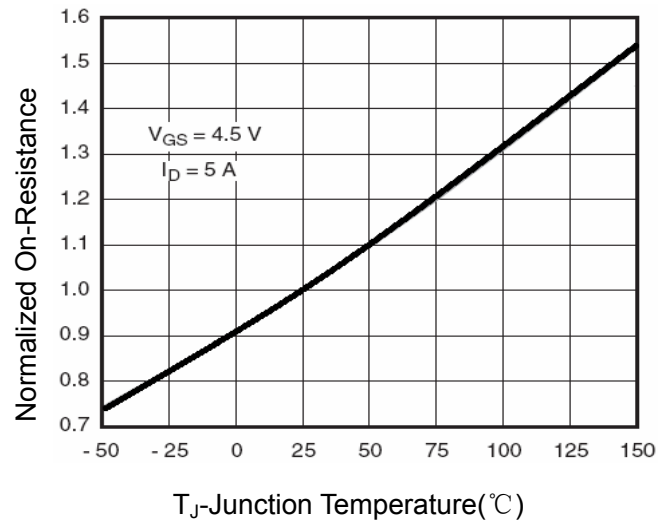
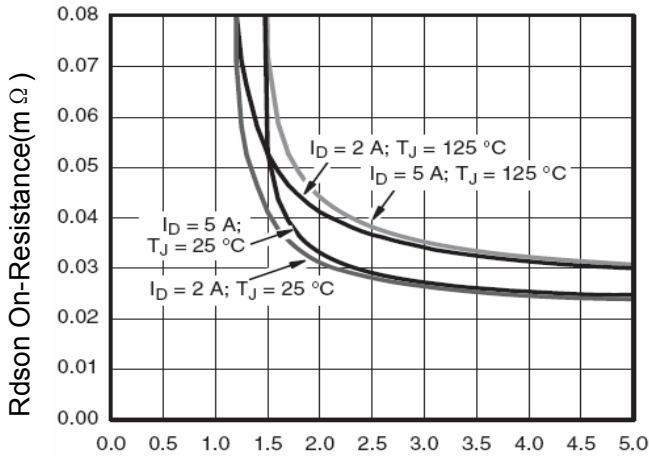
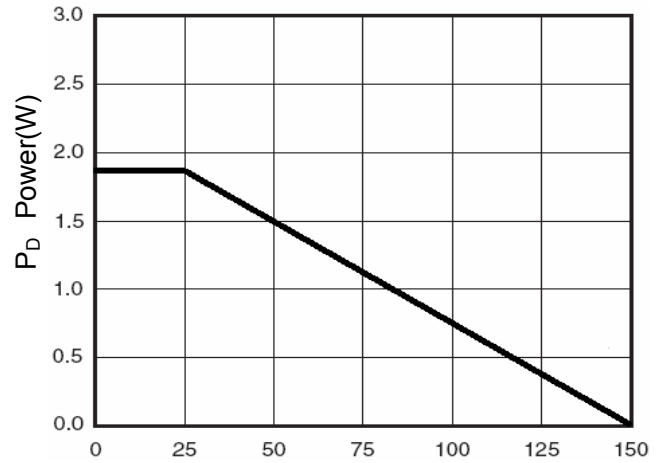


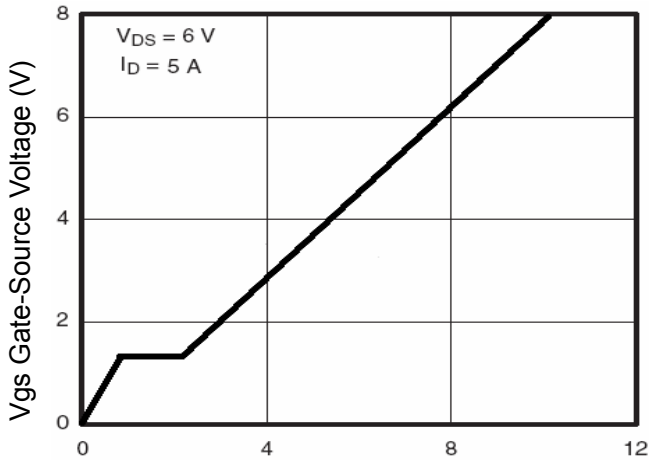
Figure 6 Drain-Source On-Resistance



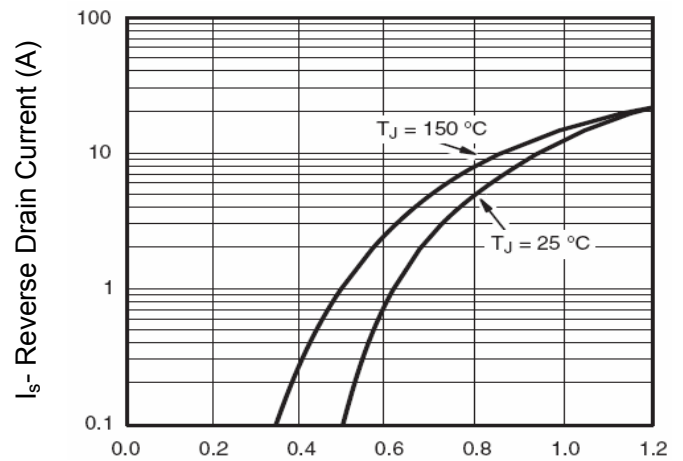
Vgs Gate-Source Voltage (V)
Figure 7 Rdson vs Vgs



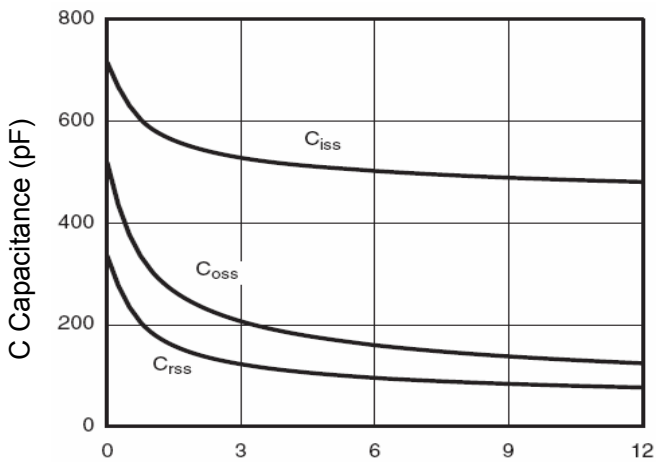
TJ-Junction Temperature(°C)
Figure 8 Power Dissipation



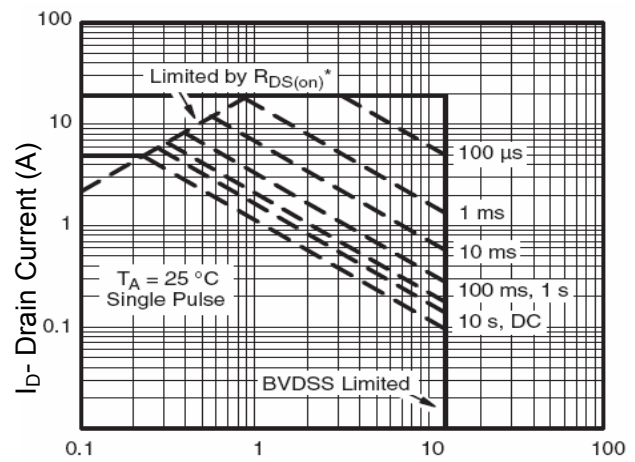
Qg Gate Charge (nC)
Figure 9 Gate Charge



Vds Drain-Source Voltage (V)
Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)
Figure 11 Capacitance vs Vds



Vds Drain-Source Voltage (V)
Figure 12 Safe Operation Area

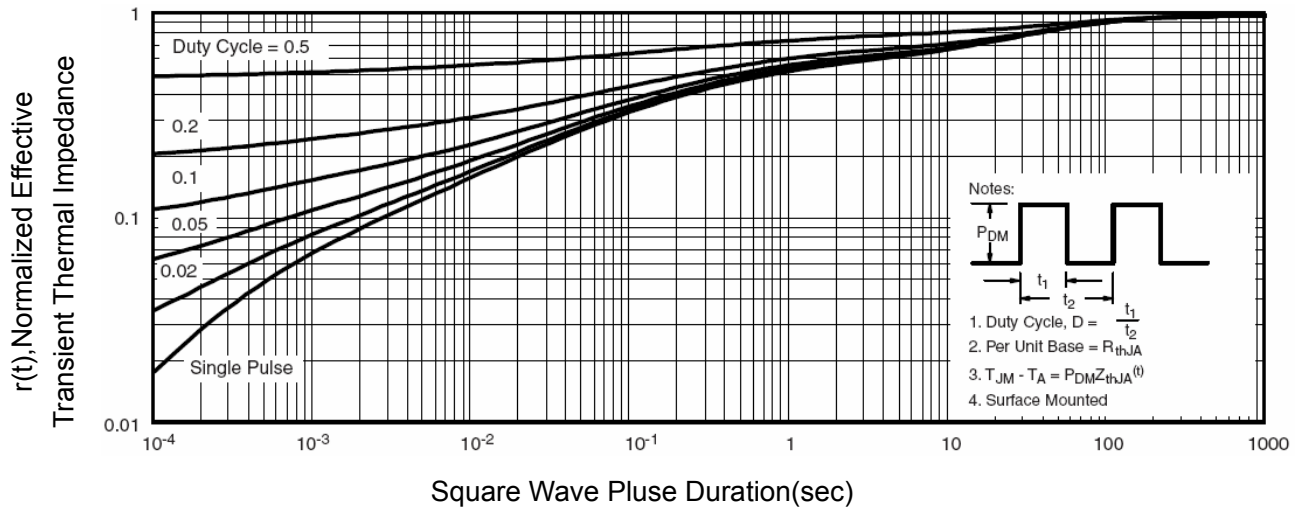


Figure 13 Normalized Maximum Transient Thermal Impedance



P- Channel Typical Electrical and Thermal Characteristics (Curves)

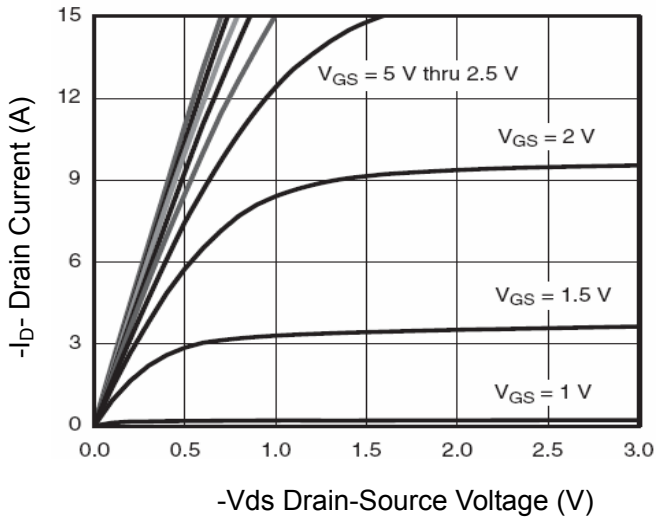


Figure 1 Output Characteristics

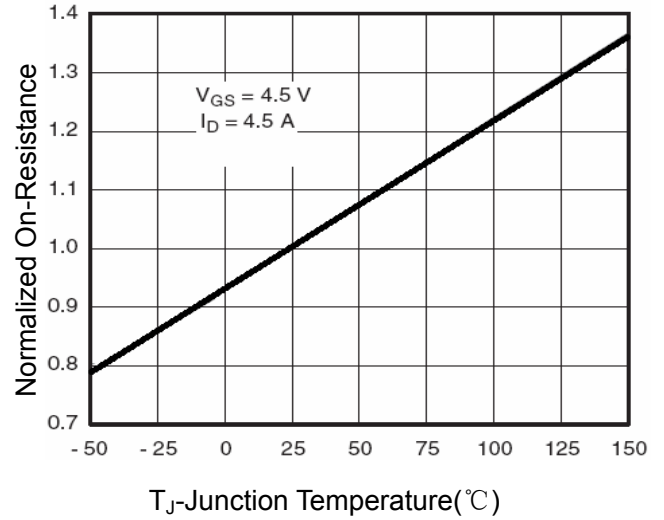


Figure 4 Rdson-Junction Temperature

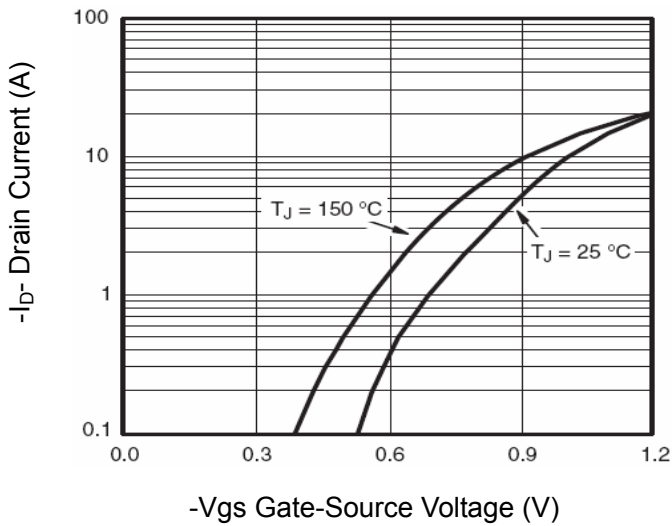


Figure 2 Transfer Characteristics

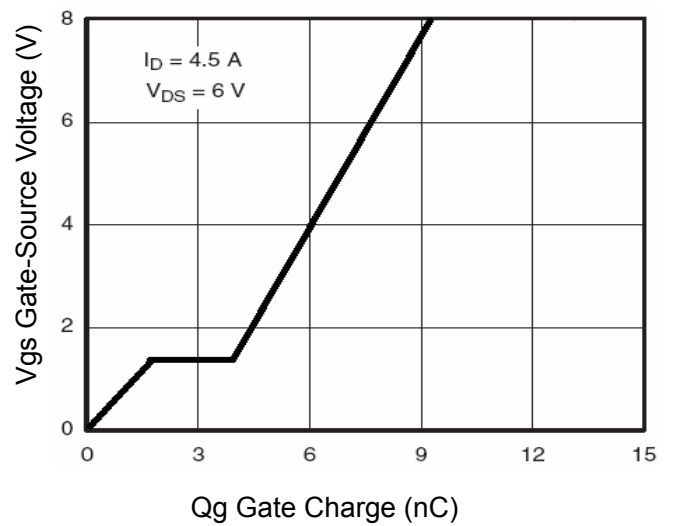


Figure 5 Gate Charge

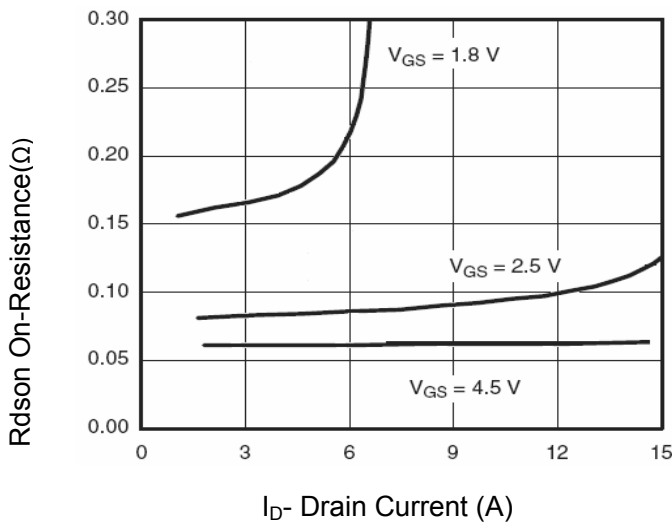


Figure 3 Rdson- Drain Current

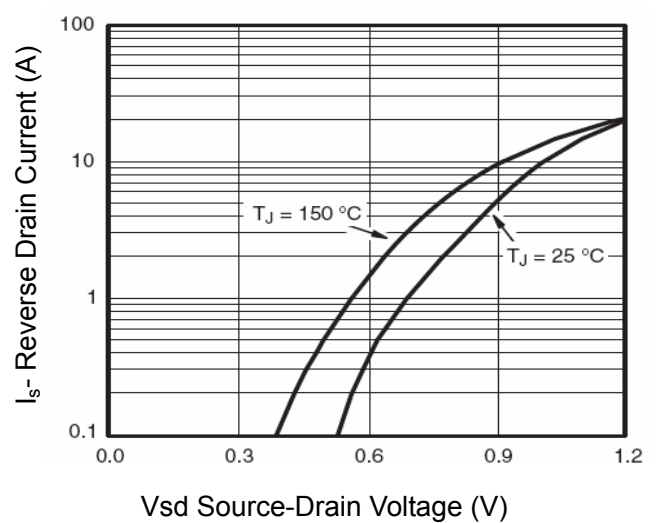


Figure 6 Source- Drain Diode Forward

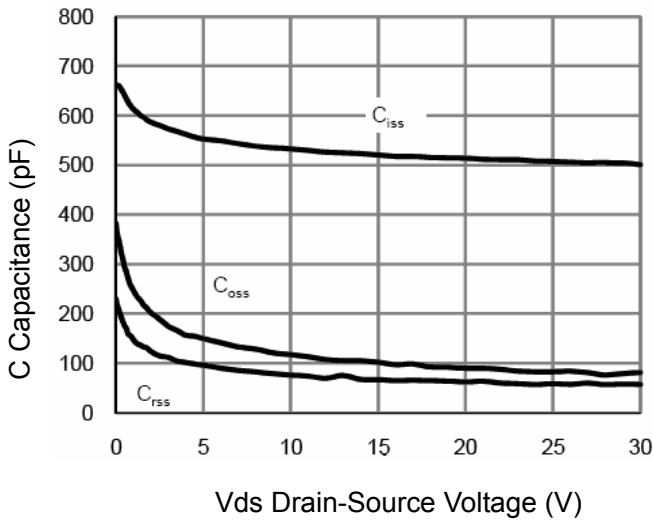


Figure 7 Capacitance vs Vds

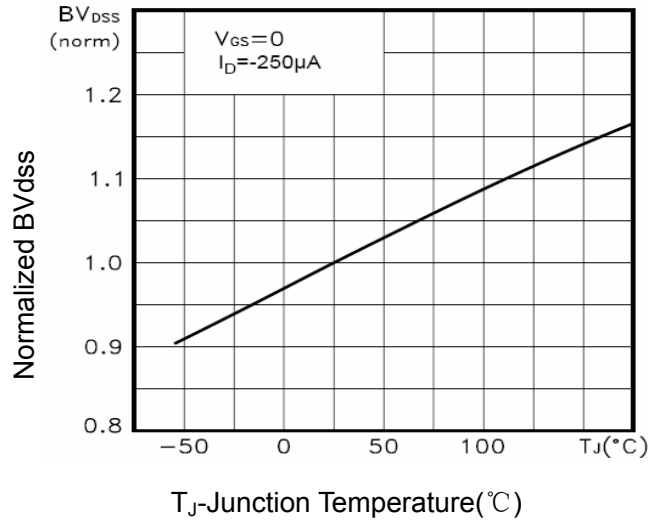


Figure 9 BV_{DSS} vs Junction Temperature

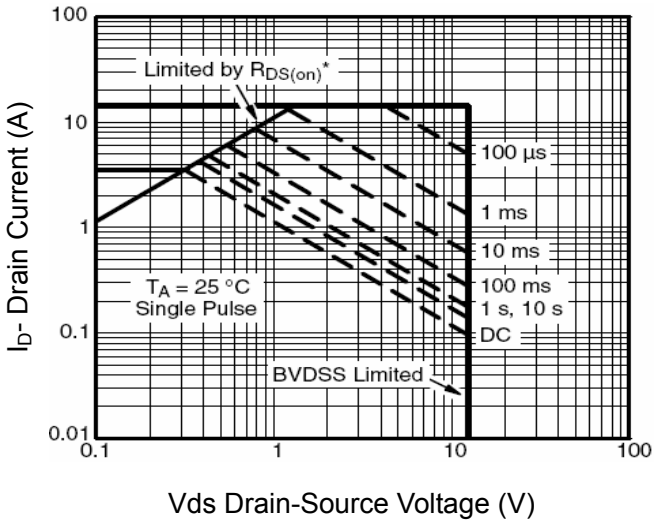


Figure 8 Safe Operation Area

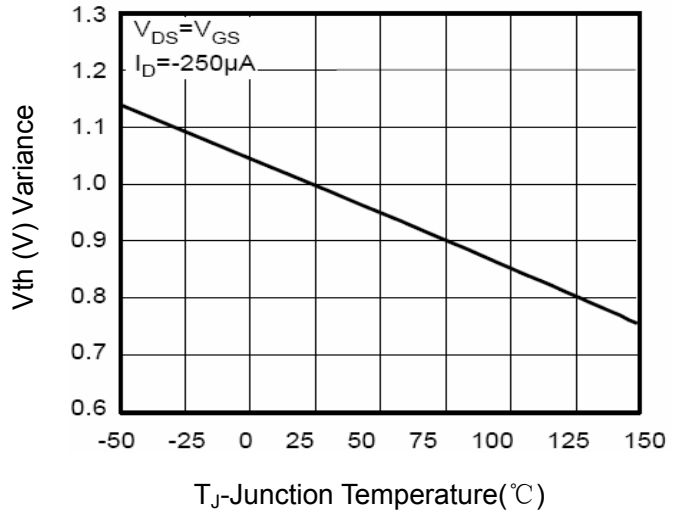


Figure 10 $V_{GS(th)}$ vs Junction Temperature

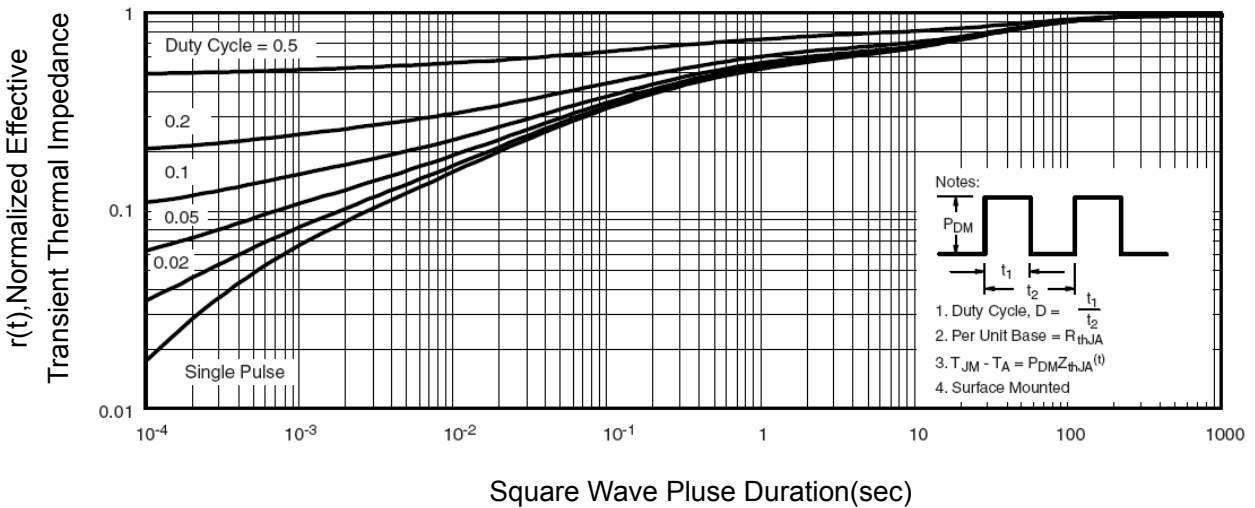
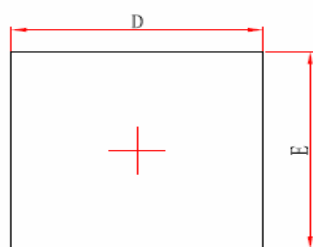


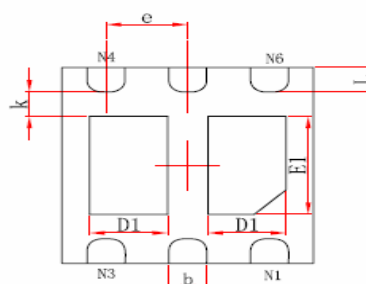
Figure 11 Normalized Maximum Transient Thermal Impedance



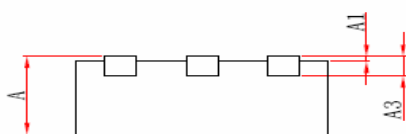
DFN2X2-6 Package Information



Top View



Bottom View



Side View

| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------------|----------------------|-------------|
| | Min. | Max. | Min. | Max. |
| A | 0.700/0.800 | 0.800/0.900 | 0.028/0.031 | 0.031/0.035 |
| A1 | 0.000 | 0.050 | 0.000 | 0.002 |
| A3 | 0.203REF. | | 0.008REF. | |
| D | 1.924 | 2.076 | 0.076 | 0.082 |
| E | 1.924 | 2.076 | 0.076 | 0.082 |
| D1 | 0.520 | 0.720 | 0.020 | 0.028 |
| E1 | 0.900 | 1.100 | 0.035 | 0.043 |
| k | 0.200MIN. | | 0.008MIN. | |
| b | 0.250 | 0.350 | 0.010 | 0.014 |
| e | 0.650TYP. | | 0.026TYP. | |
| L | 0.174 | 0.326 | 0.007 | 0.013 |